

DESCRIPTION

The MXN2050M uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

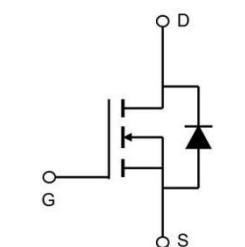
GENERAL FEATURES

- $V_{DS}=18V$, $I_D=40A$
 $R_{DS(ON)}(\text{Typ.})=4.5\text{m}\Omega$ @ $V_{GS}=4.5\text{V}$
 $R_{DS(ON)}(\text{Typ.})=6.3\text{m}\Omega$ @ $V_{GS}=2.5\text{V}$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

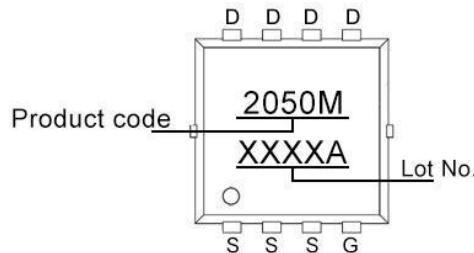
APPLICATION

- PWM applications
- Load switch

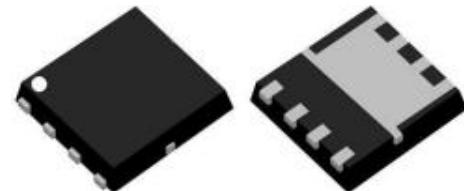
PINOUT



Schematic diagram



Marking and pin Assignment



PDFN3.3X3.3-8L top & bottom view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN2050M	-55°C to 150°C	PDFN3.3X3.3-8L	-

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	18	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	40	A
Drain Current-Continuous($T_C=100^\circ\text{C}$)	I_D	24	A
Pulsed Drain Current ^(Note1)	I_{DM}	180	A
Maximum Power Dissipation	P_D	42	W
Avalanche Current	I_{AS}	40	A
Avalanche Energy($L=0.5\text{mH}$)	E_{AS}	80	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	3	°C/W
---	-----------------	---	------

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.

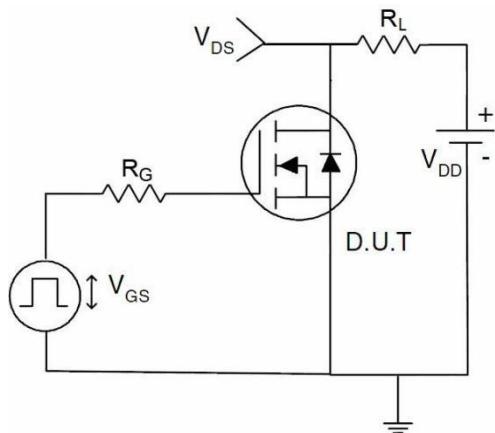
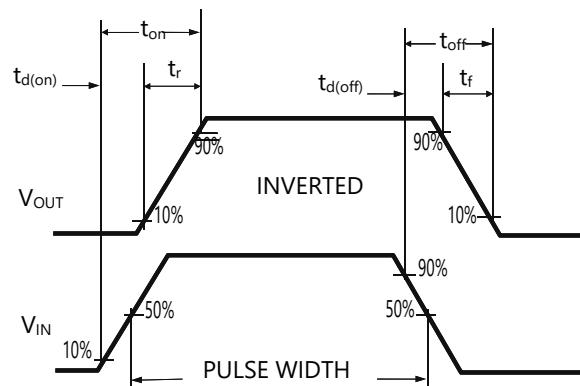
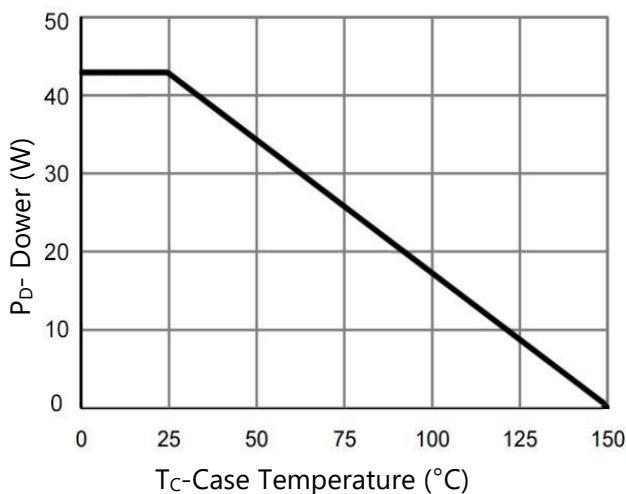
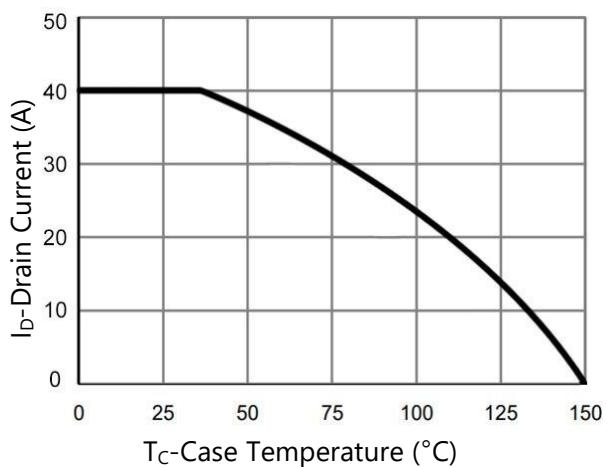
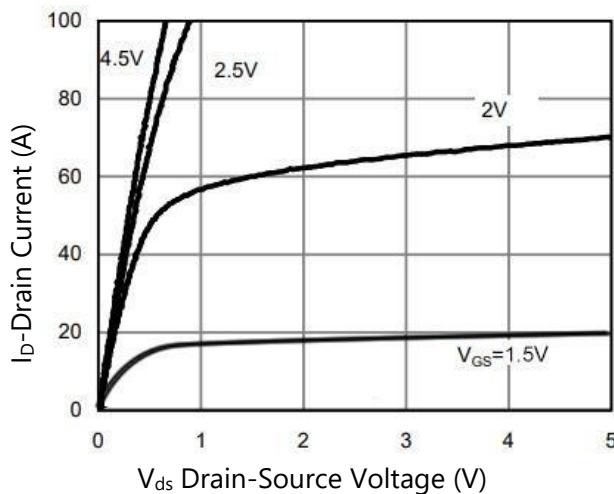
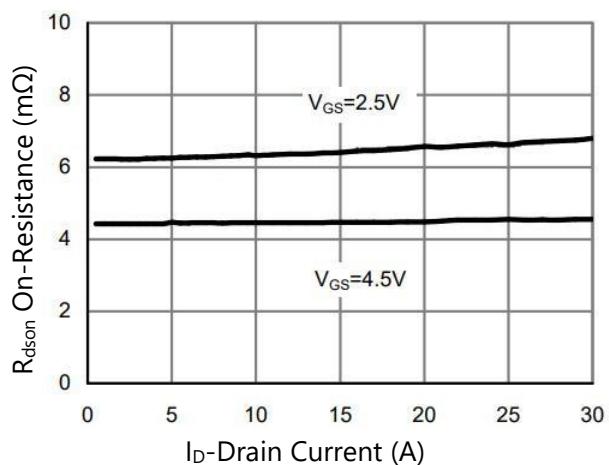

ELECTRICAL CHARACTERISTICS($T_C=25^\circ\text{C}$ unless otherwise noted)

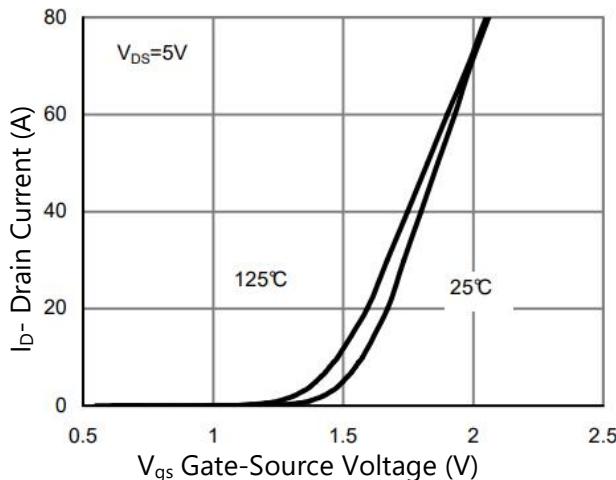
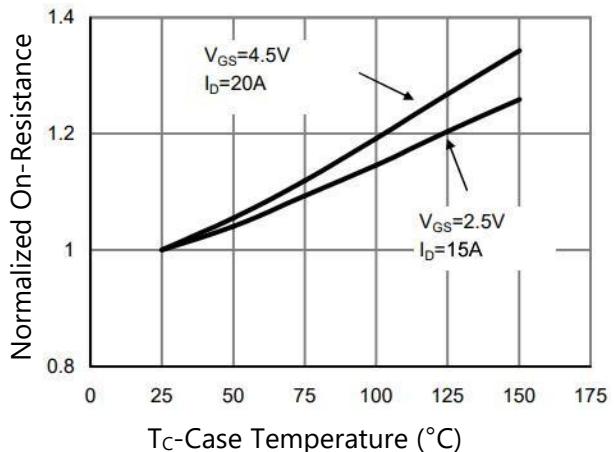
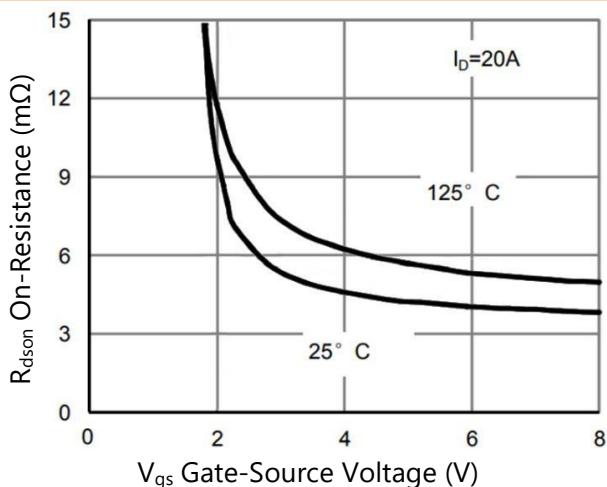
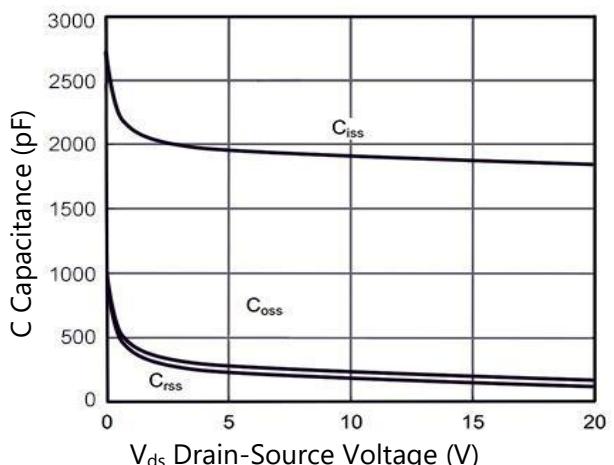
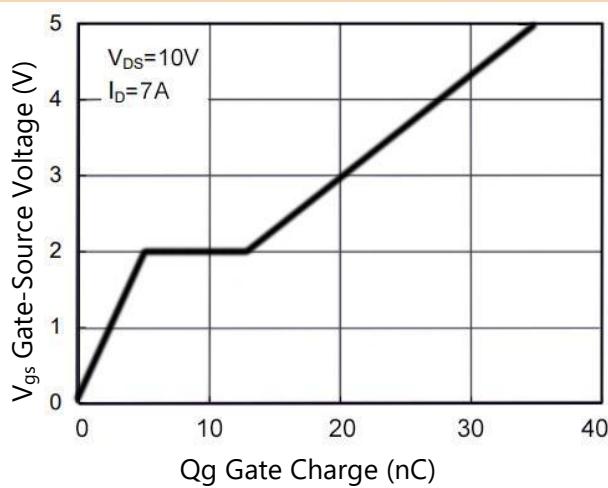
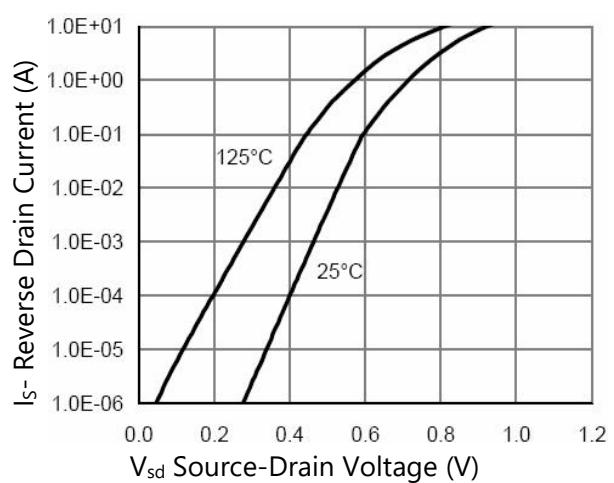
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	-	18	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=16\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics^(Note2)						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	0.45	0.7	1.1	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=20\text{A}$	-	4.5	5.5	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=15\text{A}$	-	6.3	9	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=20\text{A}$	-	100	-	S
Dynamic Characteristics^(Note3)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=10\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	1910	-	pF
Output Capacitance	C_{oss}		-	240	-	pF
Reverse Transfer Capacitance	C_{rss}		-	220	-	pF
Switching Characteristics						
Turn-on Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DS}}=10\text{V}, \text{R}_{\text{L}}=1.35\Omega, \text{V}_{\text{GS}}=5\text{V}, \text{R}_{\text{G}}=3\Omega$	-	7.5	-	nS
Turn-on Rise Time	t_{r}		-	15	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	72	-	nS
Turn-Off Fall Time	t_{f}		-	21	-	nS
Total Gate Charge	Q_{g}	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=7\text{A}, \text{V}_{\text{GS}}=4.5\text{V}$	-	31	-	nC
Gate-Source Charge	Q_{gs}		-	5.2	-	nC
Gate-Drain Charge	Q_{gd}		-	8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note2)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{S}}=1\text{A}$	-	-	1.2	V
Diode Forward Current ^(Note1)	I_{S}		-	-	40	A

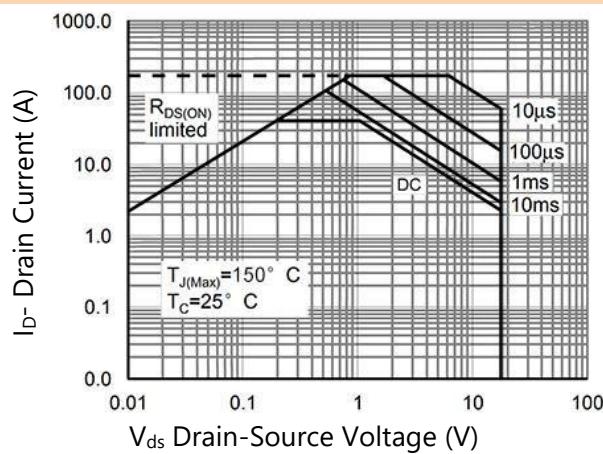
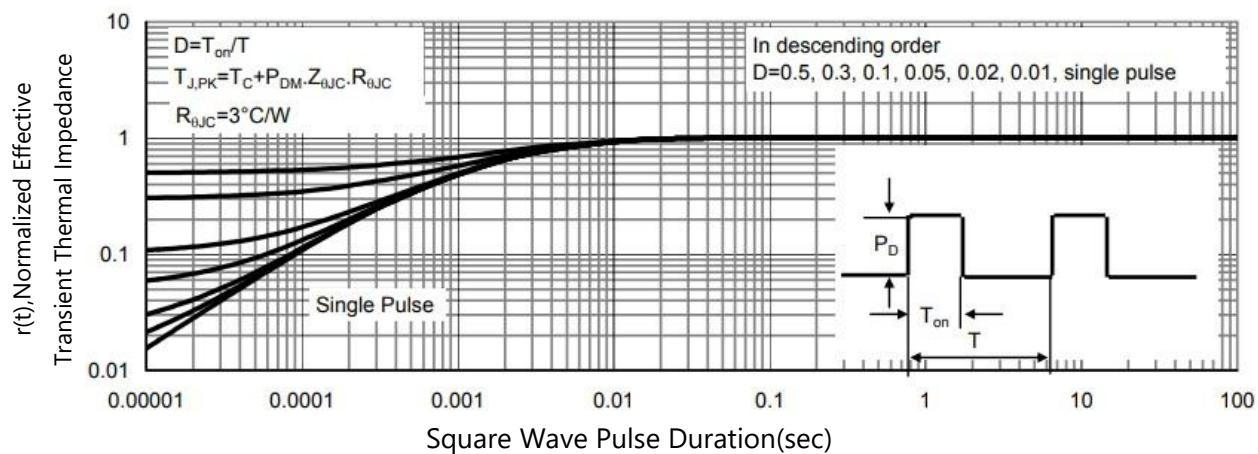
Note 1. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

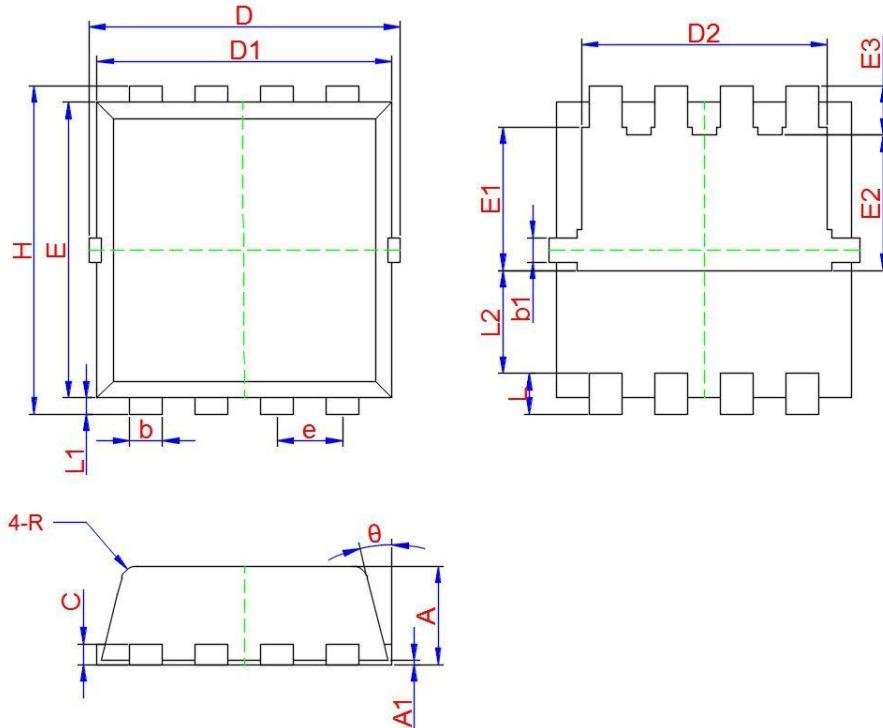
Note 3. Guaranteed by design, not subject to product.


TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 1. Switching Test Circuit

Figure 2. Switching Waveform

Figure 3. Power De-rating

Figure 4. Drain Current

Figure 5. Output Characteristics

Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 7. Transfer Characteristics

Figure 8. R_{dson} vs Case Temperature

Figure 9. R_{dson} vs V_{gs}

Figure 10. Capacitance vs V_{DS}

Figure 11. Gate Charge

Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 13. Safe Operation Area

Figure 14. Normalized Maximum Transient Thermal Impedance


PACKAGE INFORMATION

PDFN3.3X3.3-8L


Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.700	0.800	0.900
A1	0.000	0.030	0.050
b	0.240	0.300	0.350
b1	0.080	0.130	0.180
c	0.152 TYP.		
D	3.250	3.320	3.400
D1	3.050	3.150	3.250
D2	2.400	2.500	2.600
E	3.000	3.100	3.200
E1	1.350	1.450	1.550
E2	1.200	1.300	1.400
E3	0.400	0.500	0.600
e	0.650 TYP.		
H	3.200	3.300	3.400
L	0.300	0.400	0.500
L1	0.100	0.150	0.200
L2	1.130 TYP.		
R	0.200 TYP.		
θ	6°	10°	14°